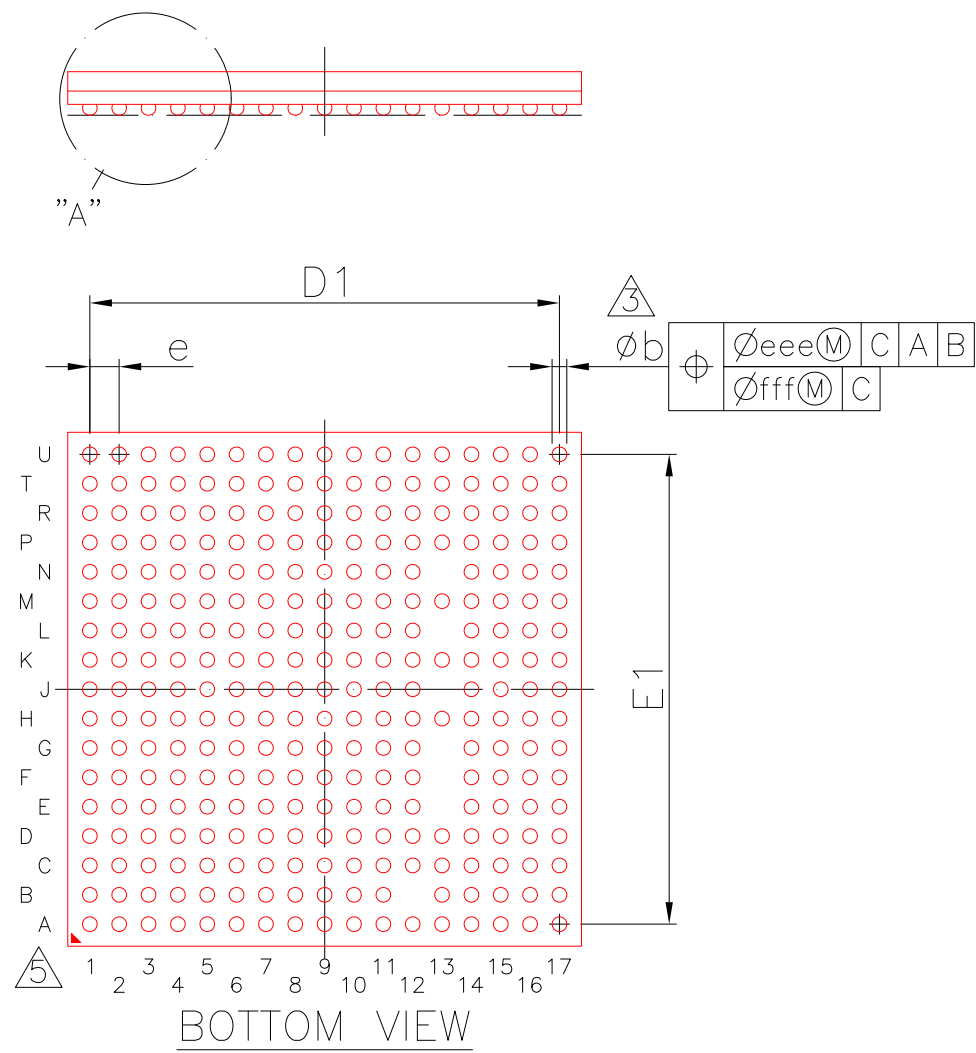


Symbol	Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.29	---	---	0.051
A1	0.25	0.30	0.35	0.010	0.012	0.014
A2	0.84	0.89	0.94	0.033	0.035	0.037
c	0.32	0.36	0.40	0.013	0.014	0.016
D	13.90	14.00	14.10	0.547	0.551	0.555
E	13.90	14.00	14.10	0.547	0.551	0.555
D1	---	12.80	---	---	0.504	---
E1	---	12.80	---	---	0.504	---
e	---	0.80	---	---	0.031	---
b	0.35	0.40	0.45	0.014	0.016	0.018
aaa	0.15			0.006		
bbb	0.10			0.004		
ddd	0.10			0.004		
eee	0.15			0.006		
fff	0.08			0.003		
MD/ME	17/17					

- NOTE :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
 4. SPECIAL CHARACTERISTICS C CLASS: bbb, ddd
 5. THE PATTERN OF PIN 1 FIDUCIAL IS FOR REFERENCE ONLY.
 6. REFERENCE DOCUMENT : JEDEC MO-207



TITLE : 282LD TFBGA (14X14 mm) PACKAGE OUTLINE			
APPR.			
PE. (M/D,B/P,S/P,S/G)		DWG NO.	
PD.		REV NO.	A
QM.		DATE	03/18/'14
CHK.		DWG.	

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REV NO	DESCRIPTION	DATE	SHT No.
A	NEW ISSUE.	03/18/'14	1/1

